2.7-V TO 5.5-V 10-BIT 3-μS QUADRUPLE DIGITAL-TO-ANALOG CONVERTERS WITH POWER DOWN

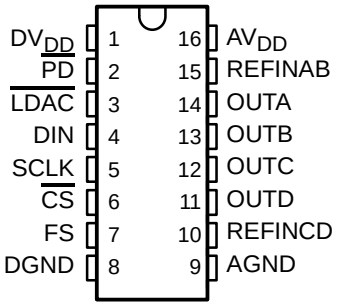
SLAS176B – DECEMBER 1997 – REVISED JULY 2002

- **Four 10-Bit D/A Converters**
- **Programmable Settling Time of 3 μs or 9 μs Typ**
- **TMS320, (Q)SPI™, and Microwire™ Compatible Serial Interface**
- **Internal Power-On Reset**
- **Low Power Consumption:**
  5.5 mW, Slow Mode – 5-V Supply
  3.3 mW, Slow Mode – 3-V Supply
- **Reference Input Buffers**
- **Voltage Output Range . . . 2× the Reference Input Voltage**
- **Monotonic Over Temperature**
- **Dual 2.7-V to 5.5-V Supply (Separate Digital and Analog Supplies)**
- **Hardware Power Down (10 nA)**
- **Software Power Down (10 nA)**
- **Simultaneous Update**

applications

- **Battery Powered Test Instruments**
- **Digital Offset and Gain Adjustment**
- **Industrial Process Controls**
- **Machine and Motion Control Devices**
- **Communications**
- **Arbitrary Waveform Generation**

D OR PW PACKAGE
(TOP VIEW)



description

The TLV5604 is a quadruple 10-bit voltage output digital-to-analog converter (DAC) with a flexible 4-wire serial interface. The 4-wire serial interface allows glueless interface to TMS320, SPI, QSPI, and Microwire serial ports. The TLV5604 is programmed with a 16-bit serial word comprised of a DAC address, individual DAC control bits, and a 10-bit DAC value.

The device has provision for two supplies: one digital supply for the serial interface (via pins DV_{DD} and DGND), and one for the DACs, reference buffers and output buffers (via pins AV_{DD} and AGND). Each supply is independent of the other, and can be any value between 2.7 V and 5.5 V. The dual supplies allow a typical application where the DAC will be controlled via a microprocessor operating on a 3-V supply (also used on pins DV_{DD} and DGND), with the DACs operating on a 5-V supply. Of course, the digital and analog supplies can be tied together.

The resistor string output voltage is buffered by a x2 gain rail-to-rail output buffer. The buffer features a Class AB output stage to improve stability and reduce settling time. A rail-to-rail output stage and a power-down mode makes it ideal for single voltage, battery based applications. The settling time of the DAC is programmable to allow the designer to optimize speed versus power dissipation. The settling time is chosen by the control bits within the 16-bit serial input string. A high-impedance buffer is integrated on the REFINAB and REFINCD terminals to reduce the need for a low source impedance drive to the terminal. REFINAB and REFINCD allow DACs A and B to have a different reference voltage then DACs C and D.

The device, implemented with a CMOS process, is available in 16-terminal SOIC and TSSOP packages. The TLV5604C is characterized for operation from 0°C to 70°C. The TLV5604I is characterized for operation from –40°C to 85°C.

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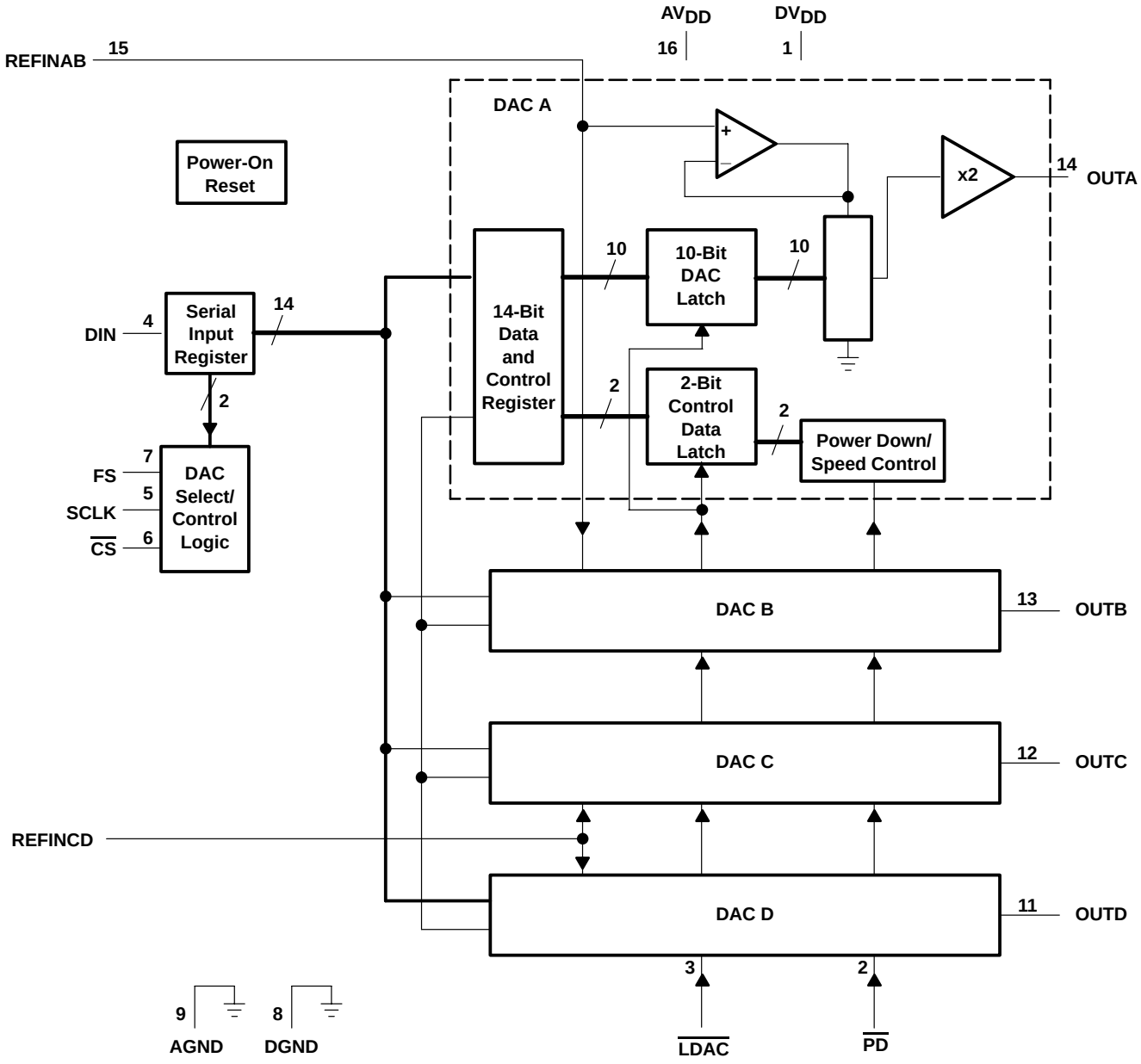
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AVAILABLE OPTIONS

T_A	PACKAGE	
	SOIC (D)	TSSOP (PW)
0°C to 70°C	TLV5604CD	TLV5604CPW
–40°C to 85°C	TLV5604ID	TLV5604IPW

functional block diagram



Terminal Functions

TERMINAL NAME	TERMINAL NO.	I/O	DESCRIPTION
AGND	9		Analog ground
AV_{DD}	16		Analog supply
$\overline{CS}$	6	I	Chip select. This terminal is active low.
DGND	8		Digital ground
DIN	4	I	Serial data input
DV_{DD}	1		Digital supply
FS	7	I	Frame sync input. The falling edge of the frame sync pulse indicates the start of a serial data frame shifted out to the TLV5604.
$\overline{PD}$	2	I	Power-down pin. Powers down all DACs (overriding their individual power down settings), and all output stages. This terminal is active low.
$\overline{LDAC}$	3	I	Load DAC. When the $\overline{LDAC}$ signal is high, no DAC output updates occur when the input digital data is read into the serial interface. The DAC outputs are only updated when $\overline{LDAC}$ is low.
REFINAB	15	I	Voltage reference input for DACs A and B.
REFINCD	10	I	Voltage reference input for DACs C and D.
SCLK	5	I	Serial Clock input
OUTA	14	O	DAC A output
OUTB	13	O	DAC B output
OUTC	12	O	DAC C output
OUTD	11	O	DAC D output

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, (DV_{DD}, AV_{DD} to GND) . . . . . 7 V
Supply voltage difference, (AV_{DD} to DV_{DD}) . . . . . –2.8 V to 2.8 V
Digital input voltage range . . . . . –0.3 V to DV_{DD} + 0.3 V
Reference input voltage range . . . . . –0.3 V to AV_{DD} + 0.3 V
Operating free-air temperature range, T_A: TLV5604C . . . . . 0°C to 70°C
TLV5604I . . . . . –40°C to 85°C
Storage temperature range, T_{stg} . . . . . –65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, AV_{DD}, DV_{DD}	5-V supply	4.5	5	5.5	V
	3-V supply	2.7	3	3.3	
High-level digital input voltage, V_{IH}	DV_{DD} = 2.7 V	2			V
	DV_{DD} = 5.5 V	2.4			
Low-level digital input voltage, V_{IL}	DV_{DD} = 2.7 V			0.6	V
	DV_{DD} = 5.5 V			1	
Reference voltage, V_{ref} to REFINAB, REFINCD terminal	5-V supply (see Note 1)	0	2.048	AV_{DD}–1.5	V
	3-V supply (see Note 1)	0	1.024	AV_{DD}–1.5	
Load resistance, R_L		2	10		kΩ
Load capacitance, C_L				100	pF
Serial clock rate, SCLK				20	MHz
Operating free-air temperature	TLV5604C	0		70	°C
	TLV5604I	–40		85	

NOTE 1: Voltages greater than $AV_{DD}/2$ will cause output saturation for large DAC codes.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

static DAC specifications

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
	Resolution			10			bits
	Integral nonlinearity (INL), end point adjusted		See Note 2			±1	LSB
	Differential nonlinearity (DNL)		See Note 3		±0.1	±1	LSB
E_{ZS}	Zero scale error (offset error at zero scale)		See Note 4			±12	mV
	Zero scale error temperature coefficient		See Note 5		10		ppm/°C
E_G	Gain error		See Note 6			±0.6	%of FS voltage
	Gain error temperature coefficient		See Note 7		10		ppm/°C
PSRR	Power supply rejection ratio	Zero scale gain	See Notes 8 and 9		–80		dB
		Gain			–80		

NOTES: 2. The relative accuracy or integral nonlinearity (INL) sometimes referred to as linearity error, is the maximum deviation of the output from the line between zero and full scale excluding the effects of zero code and full-scale errors.
3. The differential nonlinearity (DNL) sometimes referred to as differential error, is the difference between the measured and ideal 1 LSB amplitude change of any two adjacent codes. Monotonic means the output voltage changes in the same direction (or remains constant) as a change in the digital input code.
4. Zero-scale error is the deviation from zero voltage output when the digital input code is zero.
5. Zero-scale-error temperature coefficient is given by: E_{ZS} TC = $[E_{ZS}(T_{max}) – E_{ZS}(T_{min})]/V_{ref} \times 10^6/(T_{max} – T_{min})$.
6. Gain error is the deviation from the ideal output ($2V_{ref} – 1$ LSB) with an output load of 10 kΩ excluding the effects of the zero-error.
7. Gain temperature coefficient is given by: E_G TC = $[E_G(T_{max}) – E_G(T_{min})]/V_{ref} \times 10^6/(T_{max} – T_{min})$.
8. Zero-scale-error rejection ratio (EZS–RR) is measured by varying the AV_{DD} from 5 ±0.5 V and 3 ±0.3 V dc, and measuring the proportion of this signal imposed on the zero-code output voltage.
9. Gain-error rejection ratio (EG-RR) is measured by varying the AV_{DD} from 5 ±0.5 V and 3 ±0.3 V dc and measuring the proportion of this signal imposed on the full-scale output voltage after subtracting the zero scale change.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

individual DAC output specifications

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_O	Voltage output	R_L = 10 kΩ	0		AV_{DD}–0.4	V
	Output load regulation accuracy	R_L = 2 kΩ vs 10 kΩ		0.1	0.25	% of FS voltage

reference input (REFINAB, REFINCD)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_I	Input voltage range	See Note 10		0		AV_{DD}–1.5	V
R_I	Input resistance				10		MΩ
C_I	Input capacitance				5		pF
	Reference feed through	REFIN = 1 V_{pp} at 1 kHz + 1.024 V dc (see Note 11)			–75		dB
	Reference input bandwidth	REFIN = 0.2 V_{pp} + 1.024 V dc	Slow		0.5		MHz
			Fast		1		

NOTES: 10. Reference input voltages greater than V_{DD}/2 will cause output saturation for large DAC codes.
11. Reference feedthrough is measured at the DAC output with an input code = 000 hex and a $V_{ref(REFINAB or REFINCD)}$ input = 1.024 Vdc + 1 V_{pp} at 1 kHz.

digital inputs (D0–D11, $\overline{CS}$, WEB, $\overline{LDAC}$, $\overline{PD}$)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{IH}	High-level digital input current	$V_I = DV_{DD}$			±1	μA
I_{IL}	Low-level digital input current	V_I = 0 V			±1	μA
C_I	Input capacitance			3		pF

power supply

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
I_{DD}	Power supply current	5-V supply, No load, Clock running	Slow		1.4	2.2	mA
			Fast		3.5	5.5	
		3-V supply, No load, Clock running	Slow		1	1.5	mA
			Fast		3	4.5	
	Power down supply current, See Figure 12				10		nA

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

analog output dynamic performance

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
SR	Output slew rate	C_L = 100 pF, R_L = 10 kΩ, V_O = 10% to 90%, V_{ref} = 2.048 V, 1024 V	Fast		5		V/μs
			Slow		1		V/μs
t_S	Output settling time	To ± 0.5 LSB, C_L = 100 pF, R_L = 10 kΩ, See Notes 12 and 14	Fast		2.5	4	μs
			Slow		8.5	18	
$t_{S(c)}$	Output settling time, code to code	To ± 0.5 LSB, C_L = 100 pF, R_L = 10 kΩ, See Note 13	Fast		1		μs
			Slow		2		
	Glitch energy	Code transition from 7FF to 800			10		nV-sec
SNR	Signal-to-noise ratio	Sinewave generated by DAC, Reference voltage = 1.024 at 3 V and 2.048 at 5 V, f_S = 400 KSPS, f_{OUT} = 1.1 kHz sinewave, C_L = 100 pF, R_L = 10 kΩ, BW = 20 kHz			68		dB
S/(N+D)	Signal to noise + distortion				65		
THD	Total harmonic Distortion				–68		
SFDR	Spurious free dynamic range				70		

NOTES: 12. Settling time is the time for the output signal to remain within ± 0.5LSB of the final measured value for a digital input code change of 020 hex to 3FF hex or 3FF hex to 020 hex.
13. Settling time is the time for the output signal to remain within ± 0.5LSB of the final measured value for a digital input code change of one count, 1FF hex to 200 hex.
14. Limits are ensured by design and characterization, but are not production tested.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

digital input timing requirements

		MIN	NOM	MAX	UNIT
$t_{su(CS–FS)}$	Setup time, $\overline{CS}$ low before FS↓	10			ns
$t_{su(FS–CK)}$	Setup time, FS low before first negative SCLK edge	8			ns
$t_{su(C16–FS)}$	Setup time, sixteenth negative SCLK edge after FS low on which bit D0 is sampled before rising edge of FS	10			ns
$t_{su(C16–CS)}$	Setup time. The first positive SCLK edge after D0 is sampled before $\overline{CS}$ rising edge. If FS is used instead of the SCLK positive edge to update the DAC, then the setup time is between the FS rising edge and $\overline{CS}$ rising edge.	10			ns
t_{wH}	Pulse duration, SCLK high	25			ns
t_{wL}	Pulse duration, SCLK low	25			ns
$t_{su(D)}$	Setup time, data ready before SCLK falling edge	8			ns
$t_{h(D)}$	Hold time, data held valid after SCLK falling edge	5			ns
$t_{wH(FS)}$	Pulse duration, FS high	20			ns

PARAMETER MEASUREMENT INFORMATION

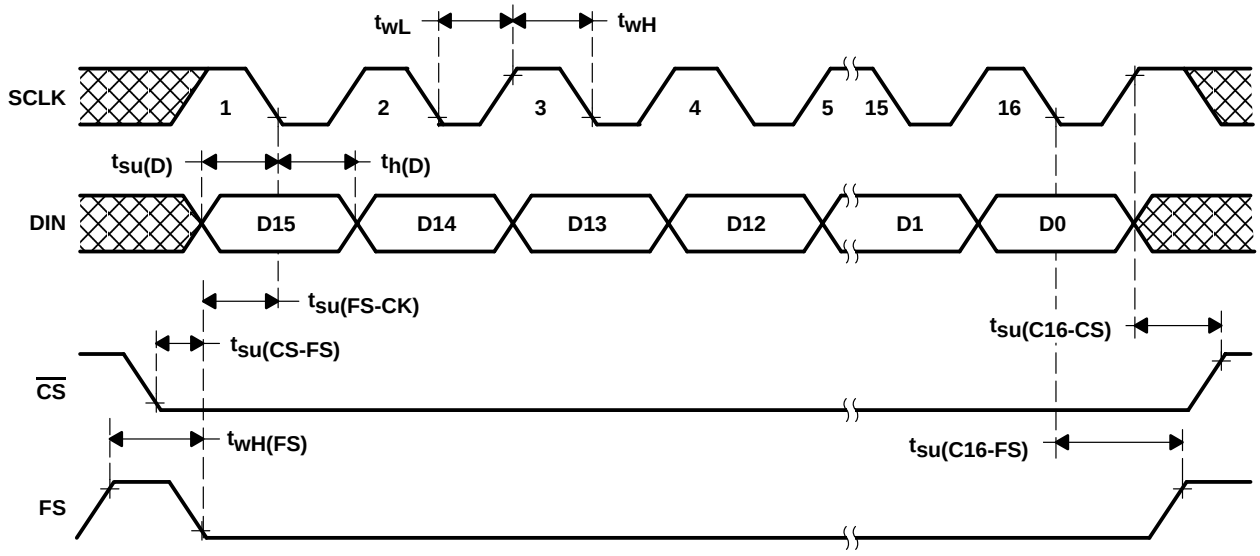


Figure 1. Timing Diagram

TYPICAL CHARACTERISTICS

LOAD REGULATION

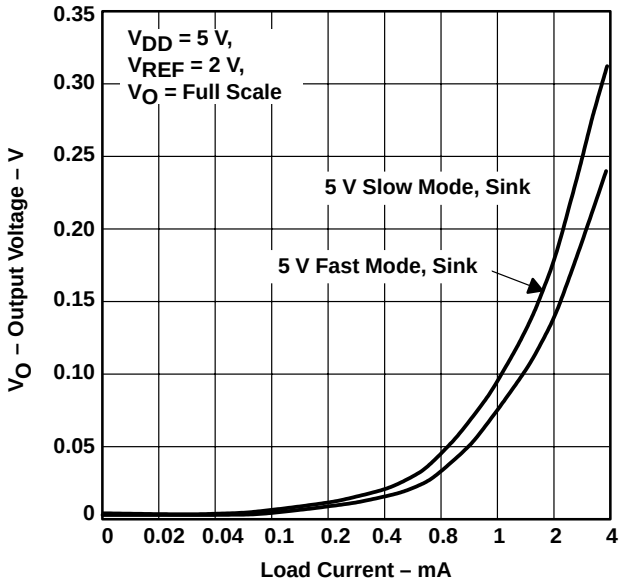


Figure 2

LOAD REGULATION

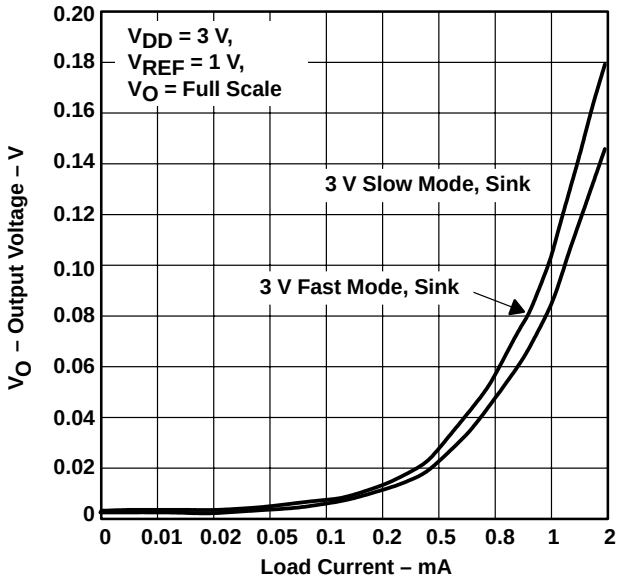


Figure 3

LOAD REGULATION

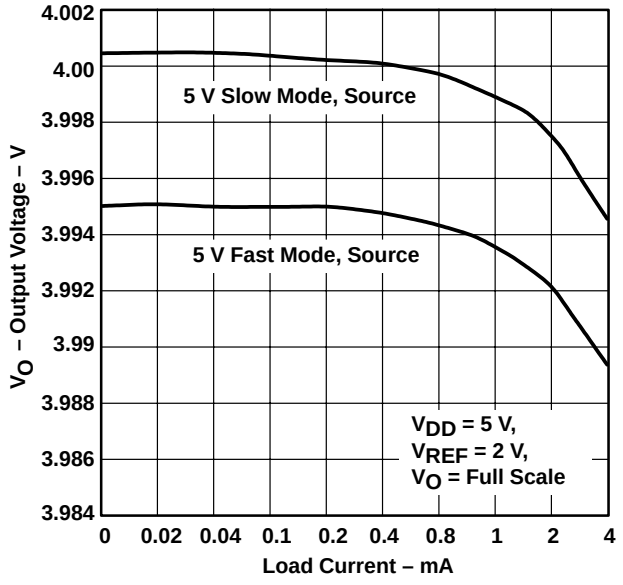


Figure 4

LOAD REGULATION

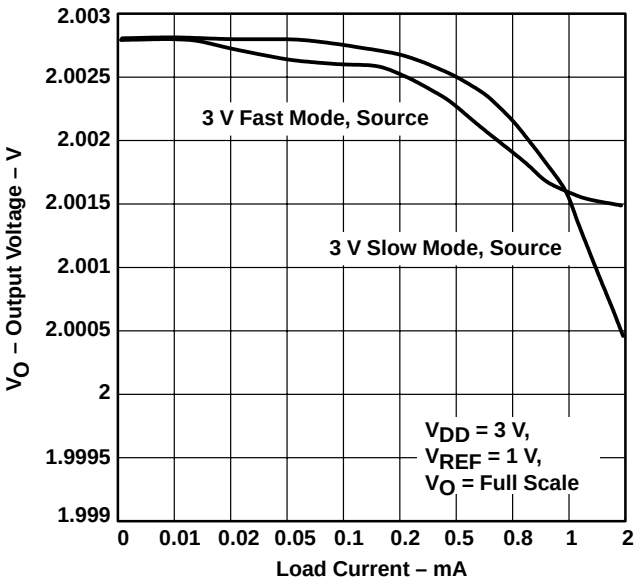


Figure 5

TYPICAL CHARACTERISTICS

SUPPLY CURRENT
vs
TEMPERATURE

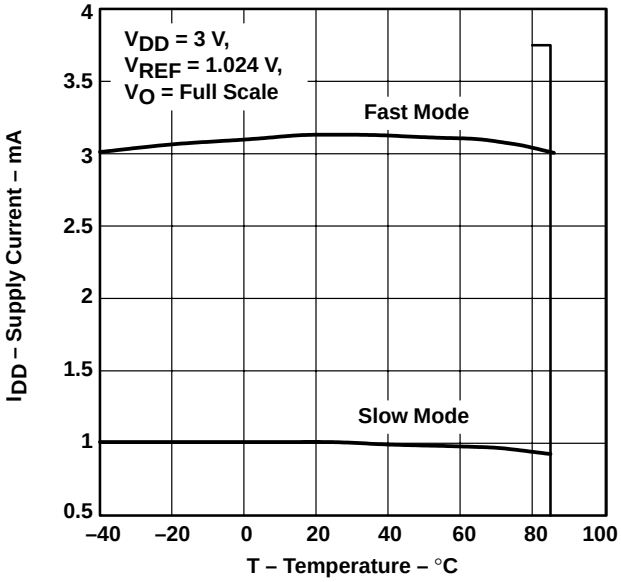


Figure 6

SUPPLY CURRENT
vs
TEMPERATURE

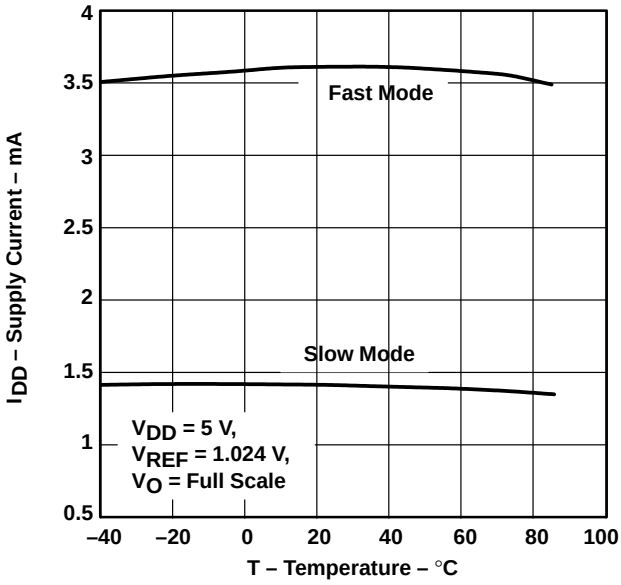


Figure 7

TOTAL HARMONIC DISTORTION
vs
FREQUENCY

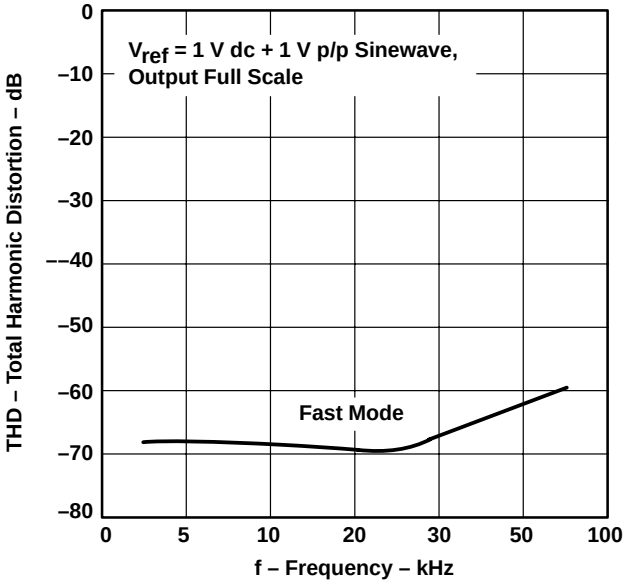


Figure 8

TOTAL HARMONIC DISTORTION
vs
FREQUENCY

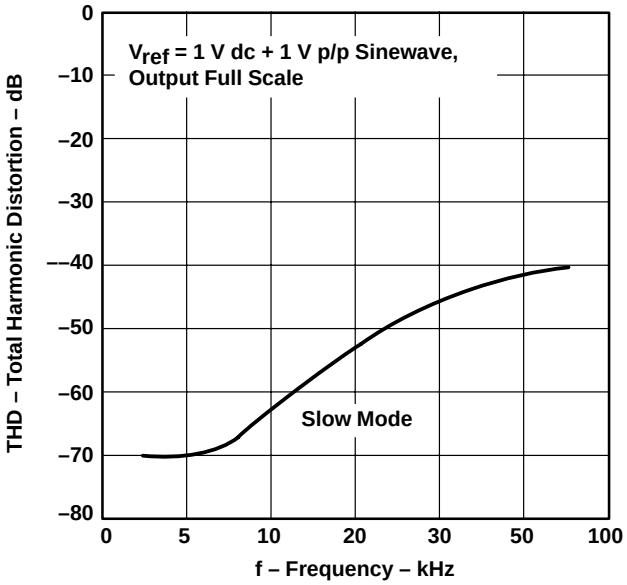


Figure 9

TYPICAL CHARACTERISTICS

TOTAL HARMONIC DISTORTION AND NOISE vs FREQUENCY

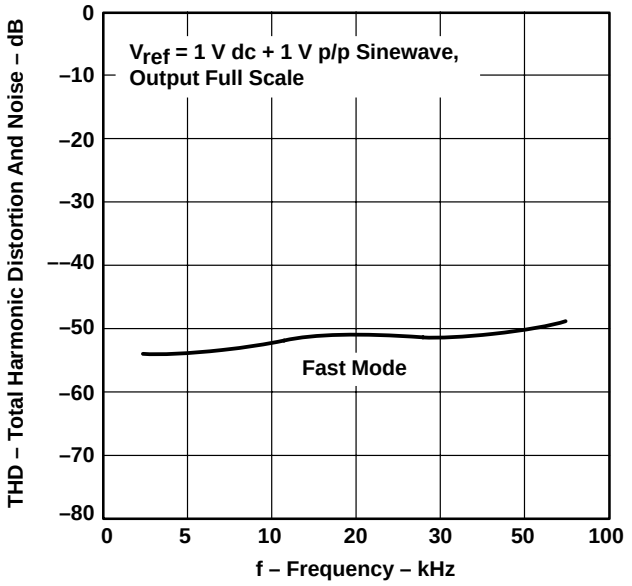


Figure 10

TOTAL HARMONIC DISTORTION AND NOISE vs FREQUENCY

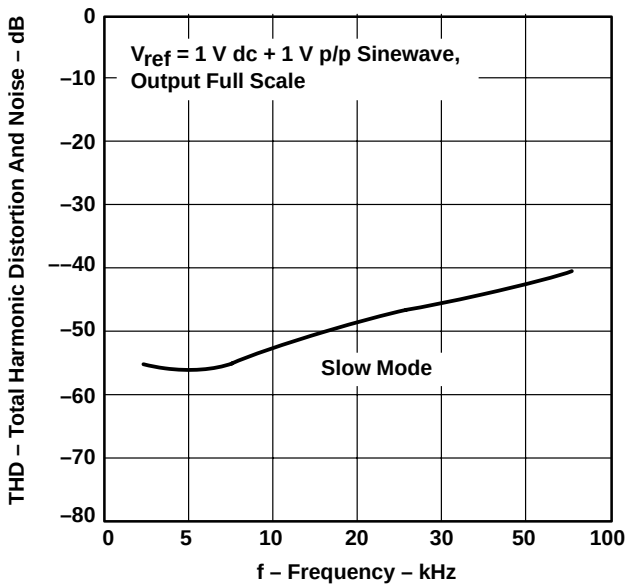


Figure 11

SUPPLY CURRENT vs TIME (WHEN ENTERING POWER-DOWN MODE)

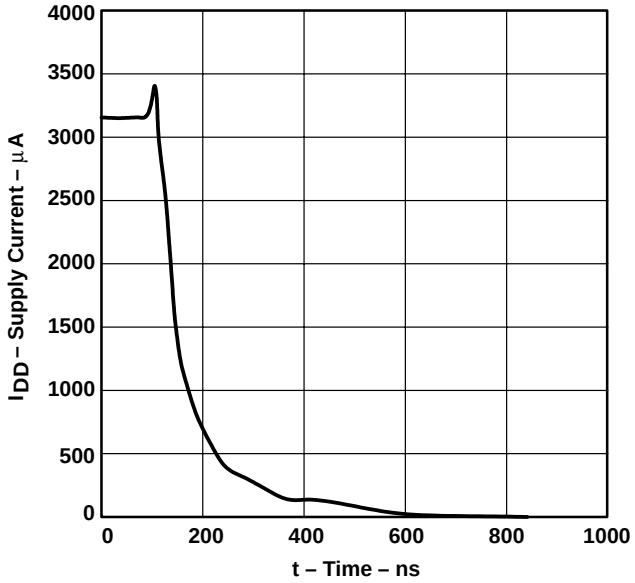


Figure 12

TYPICAL CHARACTERISTICS

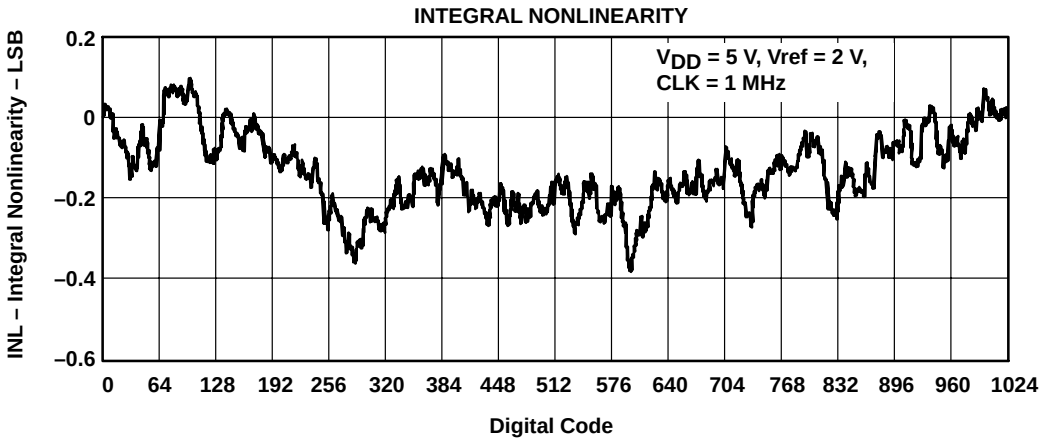


Figure 13

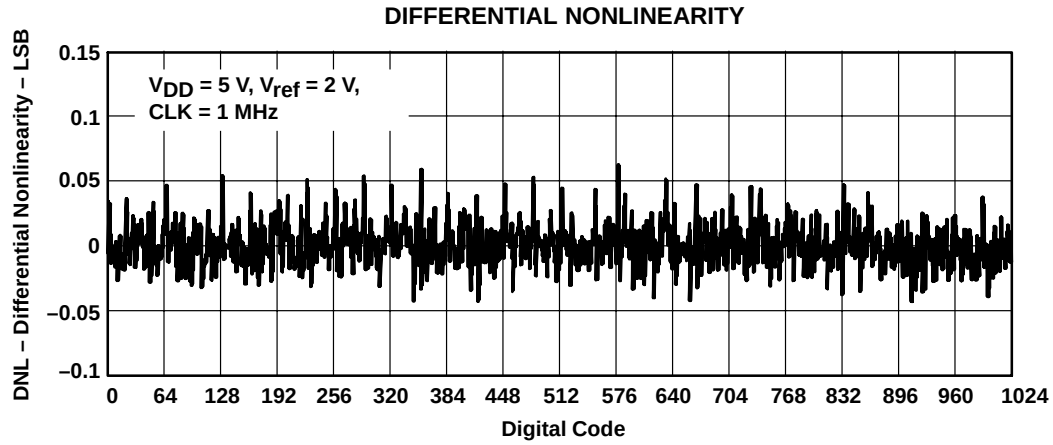


Figure 14

APPLICATION INFORMATION

general function

The TLV5604 is a 10-bit single supply DAC based on a resistor string architecture. The device consists of a serial interface, speed and power-down control logic, a reference input buffer, a resistor string, and a rail-to-rail output buffer.

The output voltage (full scale determined by external reference) is given by:

$$2 \text{ REF } \frac{\text{CODE}}{2^n} \text{ [V]}$$

Where REF is the reference voltage and CODE is the digital input value within the range of 0_{10} to 2^n–1, where n=10 (bits). The 16-bit data word, consisting of control bits and the new DAC value, is illustrated in the *data format* section. A power-on reset initially resets the internal latches to a defined state (all bits zero).

serial interface

Explanation of data transfer: First, the device has to be enabled with $\overline{CS}$ set to low. Then, a falling edge of FS starts shifting the data bit-per-bit (starting with the MSB) to the internal register on the falling edges of SCLK. After 16 bits have been transferred or FS rises, the content of the shift register is moved to the DAC latch, which updates the voltage output to the new level.

The serial interface of the TLV5604 can be used in two basic modes:

- Four wire (with chip select)
- Three wire (without chip select)

Using chip select (four wire mode), it is possible to have more than one device connected to the serial port of the data source (DSP or microcontroller). The interface is compatible with the TMS320 family. Figure 15 shows an example with two TLV5604s connected directly to a TMS320 DSP.

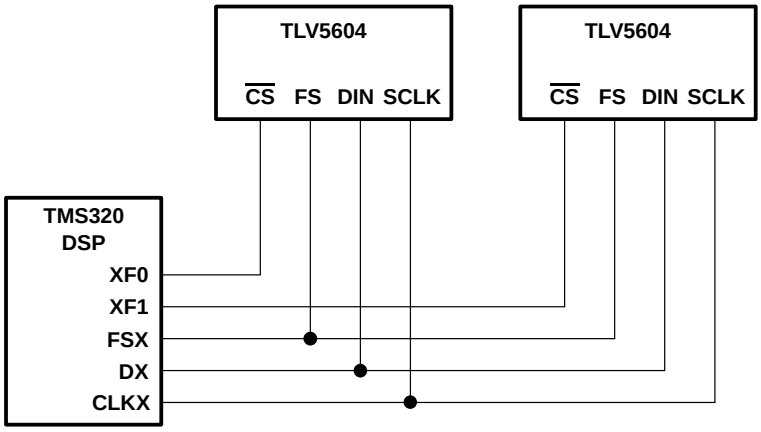


Figure 15. TMS320 Interface

APPLICATION INFORMATION

serial interface (continued)

If there is no need to have more than one device on the serial bus, then $\overline{CS}$ can be tied low. Figure 16 shows an example of how to connect the TLV5604 to a TMS320, SPI, or Microwire port using only three pins.

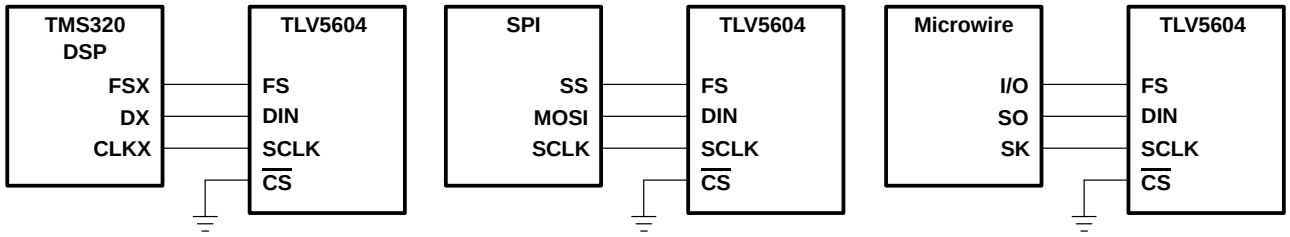


Figure 16. Three-Wire Interface

Notes on SPI and Microwire: Before the controller starts the data transfer, the software has to generate a falling edge on the I/O pin connected to FS. If the word width is 8 bits (SPI and Microwire), two write operations must be performed to program the TLV5604. After the write operation(s), the DAC output is updated automatically on the next positive clock edge following the sixteenth falling clock edge.

serial clock frequency and update rate

The maximum serial clock frequency is given by:

$$f_{SCLKmax} = \frac{1}{t_{wH(min)} + t_{wL(min)}} = 20 \text{ MHz}$$

The maximum update rate is:

$$f_{UPDATEmax} = \frac{1}{16 \left(t_{wH(min)} + t_{wL(min)} \right)} = 1.25 \text{ MHz}$$

Note that the maximum update rate is a theoretical value for the serial interface since the settling time of the TLV5604 has to be considered also.

data format

The 16-bit data word for the TLV5604 consists of two parts:

- Control bits (D15 . . . D12)
- New DAC value (D11 . . . D0)

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
A1	A0	PWR	SPD	New DAC value (10 bits)										X	X

X: don't care
SPD: Speed control bit. 1 → fast mode 0 → slow mode
PWR: Power control bit. 1 → power down 0 → normal operation

APPLICATION INFORMATION

In power down mode, all amplifiers within the TLV5604 are disabled. A particular DAC (A, B, C, D) of the TLV5604 is selected by A1 and A0 within the input word.

A1	A0	DAC
0	0	A
0	1	B
1	0	C
1	1	D

TLV5604 interfaced to TMS320C203 DSP

Hardware interfacing

Figure 17 shows an example of how to connect the TLV5604 to a TMS320C203 DSP. The serial port is configured in burst mode, with FSX generated by the TMS320C203 to provide the Frame Sync (FS) input to the TLV5604. Data is transmitted on the DX line, with the serial clock input on the CLKX line. The general-purpose input/output port bits IO0 and IO1 are used to generate the Chip Select ($\overline{CS}$) and DAC Latch Update ($\overline{LDAC}$) inputs to the TLV5604. The active low Power Down ($\overline{PD}$) is pulled high all the time to ensure the DACs are enabled.

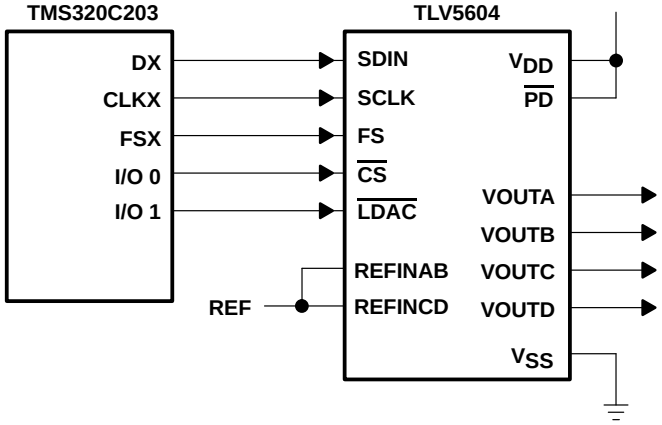


Figure 17. TLV5604 Interfaced with TMS320C203

Software

The application example generates a differential in-phase (sine) signal between the VOUTA and VOUTB pins, and it is quadrature (cosine) signal as the differential signal between VOUTC and VOUTD.

The on-chip timer is used to generate interrupts at a fixed frequency. The related interrupt service routine pulses LDAC low to update all 4 DACs simultaneously, then fetches and writes the next sample to all 4 DACs. The samples are stored in a look-up table, which describes two full periods of a sine wave.

The synchronous serial port of the DSP is used in burst mode. In this mode, the processor generates an FS pulse preceding the MSB of every data word. If multiple, contiguous words are transmitted, a violation of the tsu(C16-FS) timing requirement will occur. To avoid this, the program waits until the transmission of the previous word has been completed.

APPLICATION INFORMATION

```
;-------------------------------------------------------------------------------------;
; Processor:  TMS320C203 runnning at 40 MHz;
; Description:
;
; This program generates a differential in-phase (sine) on (OUTA–OUTB) and it's
; quadrature (cosine) as a differential signal on (OUTC–OUTD).
;
; The DAC codes for the signal samples are stored as a table of 64 12–bit values,
; describing 2 periods of a sine function. A rolling pointer is used to address the
; table location in the first period of  this waveform, from which the DAC A samples are
; read. The samples for the other 3 DACs are read at an offset to this rolling pointer:
; DAC     Function     Offset from rolling pointer;
;  A      sine                0
;  B      inverse sine        16
;  C      cosine              8
;  D      inverse cosine        24
;
; The on-chip timer is used to generate interrupts at a fixed rate. The interrupt
; service routine first pulses LDAC low to update all DACs simultaneously with the
; values which were written to them in the previous interrupt. Then all 4 DAC values are
; fetched and written out through the synchronous serial interface. Finally, the
; rolling pointer is incremented to address the next sample, ready for the next
; interrupt.
;
; © 1998, Texas Instruments Incorporated
;-------------------------------------------------------------------------------------;
; ----------I/O and memory mapped regs ------------------------------------------
             .include "regs.asm"
; --------------jump vectors-----------------------------------------------------
             .ps    0h
             b      start
             b      int1
             b      int23
             b      timer_isr
;---------------------- variables ---------------------------------------------
temp                 .equ    0060h
r_ptr                .equ    0061
iosr_stat            .equ    0062h
DACa_ptr             .equ    0063h
DACb_ptr             .equ    0064h
DACc_ptr             .equ    0065h
DACd_ptr             .equ    0066h

;--------- constants ---------------------------------------------------------
; DAC control bits to be OR'ed onto data
; all fast mode
DACa_control         .equ    01000h
DACb_control         .equ    05000h
DACc_control         .equ    09000h
DACd_control         .equ    0d000h
;----------- tables ------------------------------------------------------------
       .ds       02000h
sinevals
       .word     00800h
       .word     0097Ch
       .word     00AE9h
       .word     00C3Ah
       .word     00D61h
       .word     00E53h
       .word     00F07h
       .word     00F76h
       .word     00F9Ch
       .word     00F76h
       .word     00F07h
       .word     00E53h
       .word     00D61h
       .word     00C3Ah
```

APPLICATION INFORMATION

```
        .word     00AE9h
        .word     0097Ch
        .word     00800h
        .word     00684h
        .word     00517h
        .word     003C6h
        .word     0029Fh
        .word     001ADh
        .word     000F9h
        .word     0008Ah
        .word     00064h
        .word     0008Ah
        .word     000F9h
        .word     001ADh
        .word     0029Fh
        .word     003C6h
        .word     00517h
        .word     00684h
        .word     00800h
        .word     0097Ch
        .word     00AE9h
        .word     00C3Ah
        .word     00D61h
        .word     00E53h
        .word     00F07h
        .word     00F76h
        .word     00F9Ch
        .word     00F76h
        .word     00F07h
        .word     00E53h
        .word     00D61h
        .word     00C3Ah
        .word     00AE9h
        .word     0097Ch
        .word     00800h
        .word     00684h
        .word     00517h
        .word     003C6h
        .word     0029Fh
        .word     001ADh
        .word     000F9h
        .word     0008Ah
        .word     00064h
        .word     0008Ah
        .word     000F9h
        .word     001ADh
        .word     0029Fh
        .word     003C6h
        .word     00517h
        .word     00684h
;-------------------------------------------------------------------------------
; Main Program
;-------------------------------------------------------------------------------
        .ps    1000h
        .entry
start
;-------------------------------------------------------------------------------
; disable interrupts
;-------------------------------------------------------------------------------
        setc   INTM           ; disable maskable interrupts
        splk   #0ffffh, IFR   ; clear all interrupts
        splk   #0004h, IMR    ; timer interrupts unmasked
```

APPLICATION INFORMATION

```
;-------------------------------------------------------------------------------
;  set up the timer
;  timer period set by values in PRD and TDDR
;  period = (CLKOUT1 period) × (1+PRD) × (1+TDDR)
;  examples for TMS320C203 with 40 MHz main clock
; Timer rate      TDDR      PRD
;   80 kHz          9        24 (18h)
;   50 kHz          9        39 (27h)
;-------------------------------------------------------------------------------

prd_val.equ         0018h
tcr_val.equ  0029h

      splk   #0000h, temp     ; clear timer
      out    temp, TIM
      splk   #prd_val, temp   ; set PRD
      out    temp, PRD
      splk   #tcr_val, temp   ; set TDDR, and TRB=1 for auto-reload
      out    temp, TCR
;-------------------------------------------------------------------------------
; Configure IO0/1 as outputs to be :
; IO0  CS     – and set high
; IO1  LDAC   – and set high
;-------------------------------------------------------------------------------
      in     temp, ASPCR    ; configure as output
      lacl   temp
      or     #0003h
      sacl   temp
      out    temp, ASPCR
      in     temp, IOSR     ; set them high
      lacl   temp
      or     #0003h
      sacl   temp
      out    temp, IOSR
;-------------------------------------------------------------------------------
; set up serial port for
; SSPCR.TXM=1    Transmit mode – generate FSX
; SSPCR.MCM=1    Clock mode – internal clock source
; SSPCR.FSM=1    Burst mode
;-------------------------------------------------------------------------------
      splk   #0000Eh, temp
      out    temp, SSPCR    ; reset transmitter
      splk   #0002Eh, temp
      out    temp, SSPCR
;-------------------------------------------------------------------------------
; reset the rolling pointer
;-------------------------------------------------------------------------------
      lacl   #000h     sacl r_ptr
;-------------------------------------------------------------------------------
; enable interrupts
;-------------------------------------------------------------------------------
      clrc   INTM
; enable maskable interrupts
;-------------------------------------------------------------------------------
; loop forever!
;-------------------------------------------------------------------------------
next      idle         ;wait for interrupt
          b      next
;-------------------------------------------------------------------------------
; all else fails stop here
;-------------------------------------------------------------------------------
done      b      done   ;hang there
```

APPLICATION INFORMATION

```
;-------------------------------------------------------------------------------
; Interrupt Service Routines
;-------------------------------------------------------------------------------
int1      ret    ; do nothing and return
int23     ret    ; do nothing and return
timer_isr:
      in     iosr_stat, IOSR ; store IOSR value into variable space
      lacl   iosr_stat       ; load acc with iosr status
      and    #0FFFDh         ; reset IO1 – LDAC low
      sacl   temp      ;
      out    temp, IOSR ;

      or     #0002h          ; set IO1 – LDAC high
      sacl   temp            ;
      out    temp, IOSR      ;
      and    #0FFFEh         ; reset IO0 – CS low
      sacl   temp            ;
      out    temp, IOSR        ;
      lacl   r_ptr             ; load rolling pointer to accumulator
      add    #sinevals         ; add pointer to table start
      sacl   DACa_ptr          ; to get a pointer for next DAC a sample
      add    #08h              ; add 8 to get to DAC C pointer
      sacl   DACc_ptr
      add    #08h              ; add 8 to get to DAC B pointer
      sacl      DACb_ptr
      add    #08h              ; add 8 to get to DAC D pointer
      sacl      DACd_ptr
      mar    *,ar0             ; set ar0 as current AR

      ; DAC A
      lar       ar0, DACa_ptr ; ar0 points to DAC a sample
      lacl      *             ; get DAC a sample into accumulator
      or        #DACa_control ; OR in DAC A control bits
      sacl      temp          ;
      out       temp, SDTR    ; send data
;-------------------------------------------------------------------------------
; We must wait for transmission to complete before writing next word to the SDTR.
; TLV5604 interface does not allow the use of burst mode with the full packet rate, as
; we need a CLKX –ve edge to clock in last bit before FS goes high again, to allow SPI
; compatibility.
;-------------------------------------------------------------------------------
      rpt       #016h         ; wait long enough for this configuration
      nop                     ; of MCLK/CLKOUT1 rate

      ; DAC B
      lar       ar0, DACb_ptr ; ar0 points to DAC a sample
      lacl      *             ; get DAC a sample into accumulator
      or        #DACb_control ; OR in DAC B control bits
      sacl      temp          ;
      out       temp, SDTR    ; send data
      rpt       #016h         ; wait long enough for this configuration
      nop                     ; of MCLK/CLKOUT1 rate
```

APPLICATION INFORMATION

```
        ; DAC C
        lar       ar0, DACc_ptr ; ar0 points to DAC a sample
        lacl      *             ; get DAC a sample into accumulator
        or        #DACc_control ; OR in DAC C control bits
        sacl      temp          ;
        out       temp, SDTR    ; send data
        rpt       #016h         ; wait long enough for this configuration
        nop                     ; of MCLK/CLKOUT1 rate
    ; DAC D
    lar           ar0, DACd_ptr ; ar0 points to DAC a sample
    lacl          *           ; get DAC a sample into accumulator
    or            #DACd_control ; OR in DAC D control bits
    sacl          temp          ;
    out           temp, SDTR    ; send data
    lacl          r_ptr         ; load rolling pointer to accumulator
    add           #1h           ; increment rolling pointer
    and           #001Fh        ; count 0–31 then wrap back round
    sacl          r_ptr         ; store rolling pointer
    rpt           #016h         ; wait long enough for this configuration
    nop                         ; of MCLK/CLKOUT1 rate
    ; now take CS high again
    lacl          iosr_stat     ; load acc with iosr status
    or            #0001h        ; set IO0 – CS high
    sacl          temp          ;
    out           temp, IOSR    ;
    clrc          intm          ; re-enable interrupts
    ret                         ; return from interrupt
.end
```

APPLICATION INFORMATION

TLV5604 interfaced to MCS®51 microcontroller

hardware interfacing

Figure 18 shows an example of how to connect the TLV5604 to an MCS®51 Microcontroller. The serial DAC input data and external control signals are sent via I/O Port 3 of the controller. The serial data is sent on the RxD line, with the serial clock output on the TxD line. Port 3 bits 3, 4, and 5 are configured as outputs to provide the DAC latch update ($\overline{\text{LDAC}}$), chip select ($\overline{\text{CS}}$) and frame sync (FS) signals for the TLV5604. The active low power down pin ($\overline{\text{PD}}$) of the TLV5604 is pulled high to ensure that the DACs are enabled.

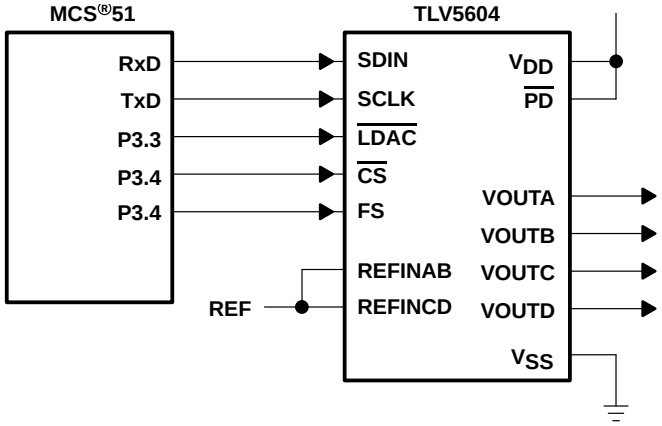


Figure 18. TLV5604 Interfaced with MCS®51

software

The example is the same as for the TMS320C203 in this datasheet, but adapted for a MCS®51 controller. It generates a differential in-phase (sine) signal between the VOUTA and VOUTB pins, and it's quadrature (cosine) signal as the differential signal between VOUTC and VOUTD.

The on-chip timer is used to generate interrupts at a fixed frequency. The related interrupt service routine pulses $\overline{\text{LDAC}}$ low to update all 4 DACs simultaneously, then fetches and writes the next sample to all 4 DACs. The samples are stored as a look-up table, which describes one full period of a sine wave.

The serial port of the controller is used in Mode 0, which transmits 8 bits of data on RxD, accompanied by a synchronous clock on TxD. Two writes concatenated together are required to write a complete word to the TLV5604. The $\overline{\text{CS}}$ and FS signals are provided in the required fashion through control of IO port 3, which has bit addressable outputs.

MCS is a registered trademark of Intel Corporation.

APPLICATION INFORMATION

```
;-------------------------------------------------------------------------------
; Processor:  80C51
;
; Description:
;
; This program generates a differential in-phase (sine) on (OUTA-OUTB) and it's
; quadrature (cosine) as a differential signal on (OUTC-OUTD).
; © 1998, Texas Instruments Incorporated
;-------------------------------------------------------------------------------
   NAME      GENIQ
   MAIN      SEGMENT   CODE
   ISR       SEGMENT   CODE
   SINTBL    SEGMENT   CODE
   VAR1      SEGMENT   DATA
   STACK     SEGMENT   IDATA
;-------------------------------------------------------------------------------
; Code start at address 0, jump to start
;-------------------------------------------------------------------------------
             CSEG   AT  0
             LJMP   start     ; Execution starts at address 0 on power-up.
;-------------------------------------------------------------------------------
; Code in the timer0 interrupt vector
;-------------------------------------------------------------------------------
             CSEG   AT  0BH
             LJMP   timer0isr ; Jump vector for timer 0 interrupt is 000Bh
;-------------------------------------------------------------------------------
; Global variables need space allocated
;-------------------------------------------------------------------------------
             RSEG   VAR1
Temp_ptr:            DS      1
rolling_ptr:         DS      1
;-------------------------------------------------------------------------------
; Interrupt service routine for timer 0 interrupts
;-------------------------------------------------------------------------------
             RSEG   ISR
timer0isr:
             PUSH   PSW
             PUSH   ACC

             CLR    INT1      ; pulse LDAC low
             SETB   INT1      ; to latch all 4 previous values at the same time
                              ; 1st thing done in timer isr => fixed period

             CLR    T0        ; set CS low
   ; The signal to be output on each DAC is a sine function.
   ; One cycle of a sine wave is held in a table @ sinevals as 32 samples of msb,
   ; lsb pairs (64 bytes). We have one pointer which rolls round this table,
   ; rolling_ptr, incrementing by 2 bytes (1 sample) on each interrupt (at the end of
   ; this routine).

   ; The DAC samples are read at an offset to this rolling pointer:
   ; DAC  Function  Offset from rolling_ptr
   ;  A   sine               0
   ;  B   inverse sine       32
   ;  C   cosine             16
   ;  D   inverse cosine     48
   MOV    DPTR,#sinevals     ; set DPTR to the start of the table of sine signal values
   MOV    R7,rolling_ptr     ; R7 holds the pointer into the sine table
   MOV    A,R7               ; get DAC A msb
   MOVC   A,@A+DPTR          ; msb of DAC A is in the ACC
   CLR    T1                 ; transmit it – set FS low
   MOV    SBUF,A             ; send it out the serial port
   INC    R7                 ; increment the pointer in R7
   MOV    A,R7               ; to get the next byte from the table
   MOVC   A,@A+DPTR          ; which is the lsb of this sample, now in ACC
```

APPLICATION INFORMATION

```
A_MSB_TX:
    JNB    TI,A_MSB_TX   ; wait for transmit to complete
    CLR    TI            ; clear for new transmit
    MOV    SBUF,A        ; and send out the lsb of DAC A

    ; DAC C next
    ; DAC C codes should be taken from 16 bytes (8 samples) further on in the sine table
    ; – this gives a cosine function
    MOV    A,R7          ; pointer in R7
    ADD    A,#0FH        ; add 15 – already done one INC
    ANL    A,#03FH       ; wrap back round to 0 if > 64
    MOV    R7,A          ; pointer back in R7

    MOVC   A,@A+DPTR     ; get DAC C msb from the table
    ORL    A,#01H        ; set control bits to DAC C address

A_LSB_TX:
    JNB    TI,A_LSB_TX   ; wait for DAC A lsb transmit to complete
    SETB   T1            ; toggle FS
    CLR    T1
    CLR    TI            ; clear for new transmit
    MOV    SBUF,A        ; and send out the msb of DAC C

    INC    R7            ; increment the pointer in R7
    MOV    A,R7          ; to get the next byte from the table
    MOVC   A,@A+DPTR     ; which is the lsb of this sample, now in ACC

C_MSB_TX:
    JNB    TI,C_MSB_TX   ; wait for transmit to complete
    CLR    TI            ; clear for new transmit
    MOV    SBUF,A        ; and send out the lsb of DAC C

    ; DAC B next
    ; DAC B codes should be taken from 16 bytes (8 samples) further on
    ; in the sine table – this gives an inverted sine function
    MOV    A,R7          ; pointer in R7
    ADD    A,#0FH        ; add 15 – already done one INC
    ANL    A,#03FH       ; wrap back round to 0 if > 64
    MOV    R7,A          ; pointer back in R7

    MOVC   A,@A+DPTR     ; get DAC B msb from the table
    ORL    A,#02H        ; set control bits to DAC B address

C_LSB_TX:
    JNB    TI,C_LSB_TX         ; wait for DAC C lsb transmit to complete
    SETB   T1                  ; toggle FS
    CLR    T1
    CLR    TI                  ; clear for new transmit
    MOV    SBUF,A              ; and send out the msb of DAC B
                               ; get DAC B LSB
    INC    R7                  ; increment the pointer in R7
    MOV    A,R7                ; to get the next byte from the table
    MOVC   A,@A+DPTR           ; which is the lsb of this sample, now in ACC

B_MSB_TX:
    JNB    TI,B_MSB_TX         ; wait for transmit to complete
    CLR    TI                  ; clear for new transmit
    MOV    SBUF,A              ; and send out the lsb of DAC B
```

APPLICATION INFORMATION

```
    ; DAC D next
    ; DAC D codes should be taken from 16 bytes (8 samples) further on in the sine table
    ; – this gives an inverted cosine function
    MOV    A,R7                ; pointer in R7
    ADD    A,#0FH              ; add 15 – already done one INC
    ANL    A,#03FH             ; wrap back round to 0 if > 64
    MOV    R7,A                ; pointer back in R7

    MOVC   A,@A+DPTR           ; get DAC D msb from the table
    ORL    A,#03H              ; set control bits to DAC D address

B_LSB_TX:
    JNB    TI,B_LSB_TX         ; wait for DAC B lsb transmit to complete
    SETB   T1                  ; toggle FS
    CLR    T1
    CLR    TI                  ; clear for new transmit
    MOV    SBUF,A              ; and send out the msb of DAC D

    INC    R7                  ; increment the pointer in R7
    MOV    A,R7                ; to get the next byte from the table
    MOVC   A,@A+DPTR           ; which is the lsb of this sample, now in ACC

D_MSB_TX:
    JNB    TI,D_MSB_TX         ; wait for transmit to complete
    CLR    TI                  ; clear for new transmit
    MOV    SBUF,A              ; and send out the lsb of DAC D

    ; increment the rolling pointer to point to the next sample
    ; ready for the next interrupt
    MOV    A,rolling_ptr
    ADD    A,#02H              ; add 2 to the rolling pointer
    ANL    A,#03FH             ; wrap back round to 0 if > 64
    MOV    rolling_ptr,A       ; store in memory again

D_LSB_TX:
    JNB TI,D_LSB_TX            ; wait for DAC D lsb transmit to complete
    CLR    TI                  ; clear for next transmit

    SETB   T1                  ; FS high
    SETB   T0                  ; CS high
    POP    ACC
    POP    PSW

    RETI
;-------------------------------------------------------------------------------
; Stack needs definition
;-------------------------------------------------------------------------------
      RSEG   STACK
      DS     10h               ; 16 Byte Stack!
```

APPLICATION INFORMATION

```
;-------------------------------------------------------------------------------
; Main program code
;-------------------------------------------------------------------------------
       RSEG   MAIN
start:
       MOV    SP,#STACK–1      ; first set Stack Pointer

       CLR    A
       MOV    SCON,A           ; set serial port 0 to mode 0
       MOV    TMOD,#02H        ; set timer 0 to mode 2 – auto-reload
       MOV    TH0,#038H        ; set TH0 for 5 kHs interrupts

       SETB   INT1             ; set LDAC = 1
       SETB   T1               ; set FS = 1
       SETB   T0               ; set CS = 1

       SETB   ET0              ; enable timer 0 interrupts
       SETB   EA               ; enable all interrupts

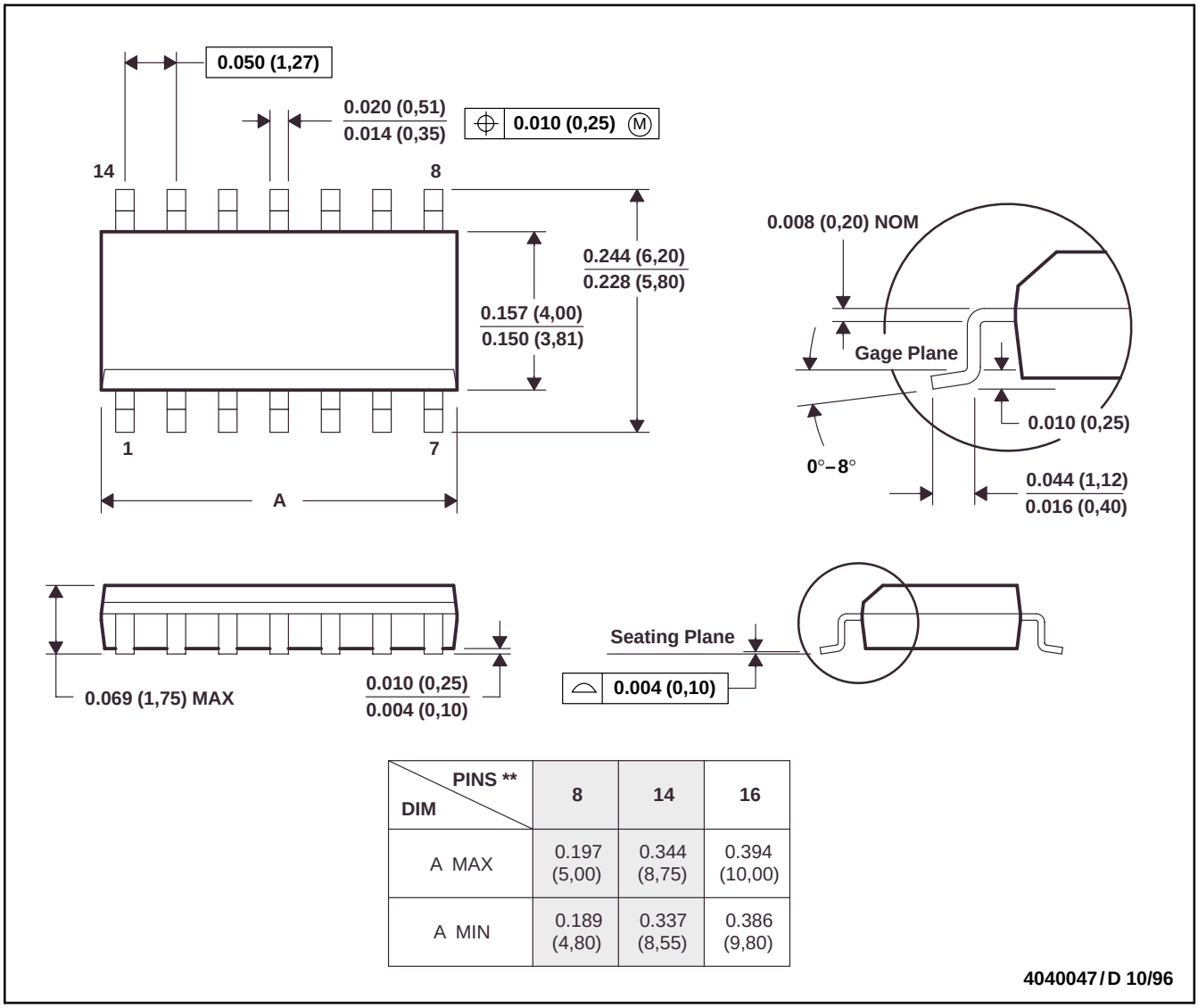
       MOV    rolling_ptr,A    ; set rolling pointer to 0
       SETB   TR0              ; start timer 0

always:
       JMP always            ; while(1) !
       RET
;-------------------------------------------------------------------------------
; Table of 32 sine wave samples used as DAC data
;-------------------------------------------------------------------------------
          RSEG      SINTBL
sinevals:
       DW        01000H
       DW        0903EH
       DW        05097H
       DW        0305CH
       DW        0B086H
       DW        070CAH
       DW        0F0E0H
       DW        0F06EH
       DW        0F039H
       DW        0F06EH
       DW        0F0E0H
       DW        070CAH
       DW        0B086H
       DW        0305CH
       DW        05097H
       DW        0903EH
       DW        01000H
       DW        06021H
       DW        0A0E8H
       DW        0C063H
       DW        040F9H
       DW        080B5H
       DW        0009FH
       DW        00051H
       DW        00026H
       DW        00051H
       DW        0009FH
       DW        080B5H
       DW        040F9H
       DW        0C063H
       DW        0A0E8H
       DW        06021H
END
```

MECHANICAL DATA

D (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PIN SHOWN



DIM \ PINS **	8	14	16
A MAX	0.197 (5,00)	0.344 (8,75)	0.394 (10,00)
A MIN	0.189 (4,80)	0.337 (8,55)	0.386 (9,80)

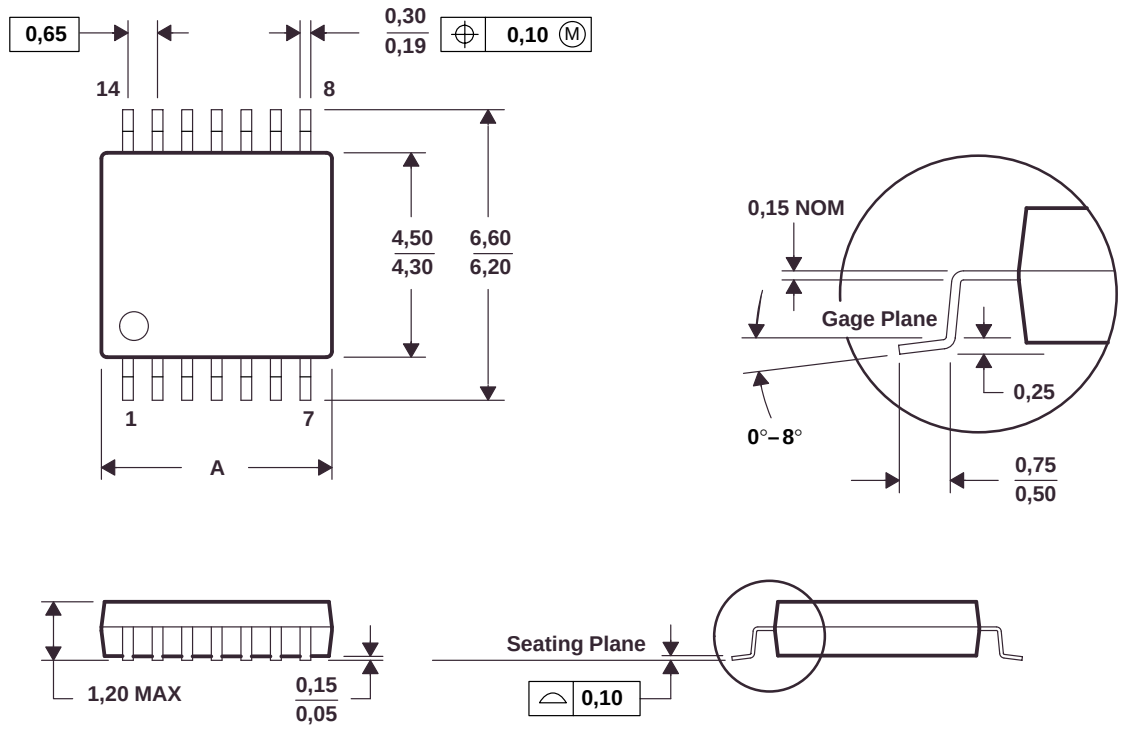
4040047/D 10/96

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
D. Falls within JEDEC MS-012

MECHANICAL DATA

PW (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PIN SHOWN



DIM \ PINS **	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/E 08/96

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
TLV5604CD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV5604CDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV5604CDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV5604CDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV5604CPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV5604CPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV5604CPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV5604CPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV5604ID	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV5604IDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV5604IPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV5604IPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV5604IPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLV5604IPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

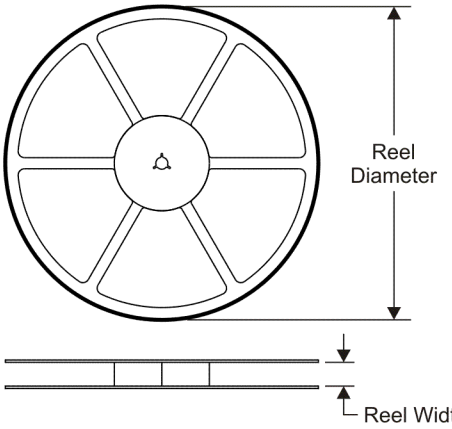
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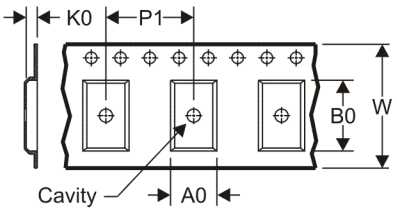
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TAPE AND REEL INFORMATION

REEL DIMENSIONS

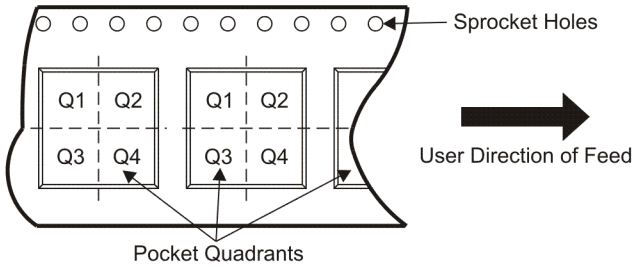


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

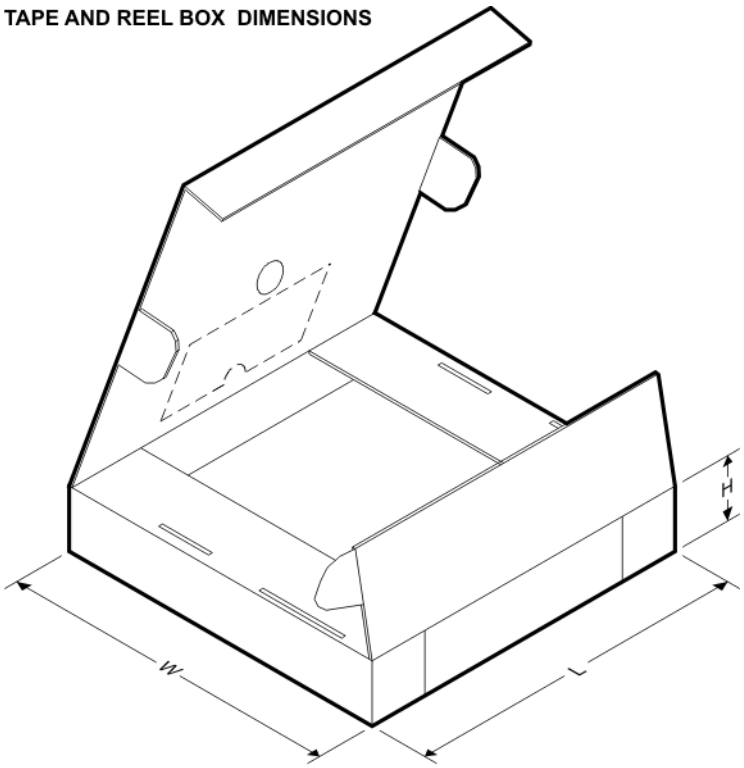
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLV5604CDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
TLV5604CPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TLV5604IPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLV5604CDR	SOIC	D	16	2500	346.0	346.0	33.0
TLV5604CPWR	TSSOP	PW	16	2000	346.0	346.0	29.0
TLV5604IPWR	TSSOP	PW	16	2000	346.0	346.0	29.0

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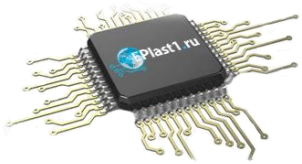
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